

# Vitronics Soltec

Electronic Assembly Equipment

TW EAE

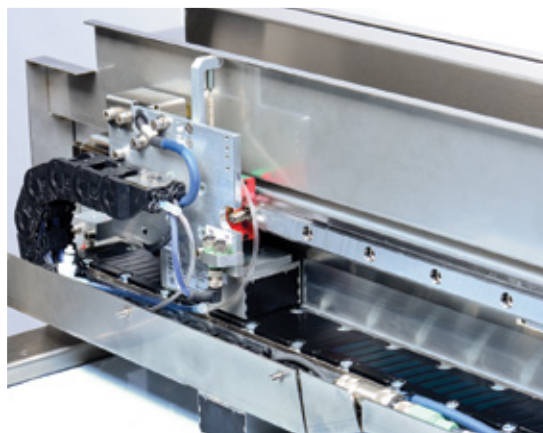
## ZEVA<sup>III+</sup>

### Selective Soldering Solution

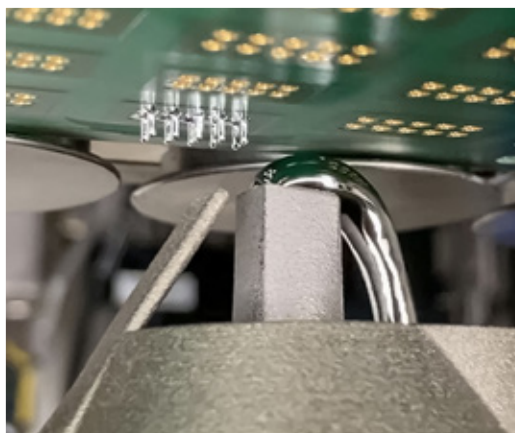
**Proven Performance  
from a Century of  
Soldering Experience**



- High frequency fluxing technology provides the most accurate process to answer the highest quality challenges
- Up to three full-size preheating units, including closed loop preheating during soldering
- Patented Bridge Prevention Technology prevents bridges from ever forming and enables the use of maintenance-free non-wettable nozzles for more consistent soldering results over time
- SmartTeach software to enable fast set up and reliable recipes
- Process control provides maximum insight on day-to-day performance



High frequency, high speed drop jet fluxing, matching every cycle time and drop size requirement



Bridge Prevention Technology prevents bridges from ever forming and enables the use of maintenance-free non-wettable nozzles for more consistent results



Up to three products can be processed simultaneously for maximized throughput



# Selective Soldering Solution

The ZEVA M+ brings the next dimension to selective point-to-point soldering. Bridge Prevention Technology prevents bridging for small pitch up to 1mm (40mil) pin to pin distance even with longer leads and increased drag speed. The tool is now integrated with a non-wettable nozzle that is 3D printed out of stainless steel and hard chromized for maintenance free, infinitely long life. The platform is supported by SmartTeach software enabling users to quickly and reliably set up a new process.

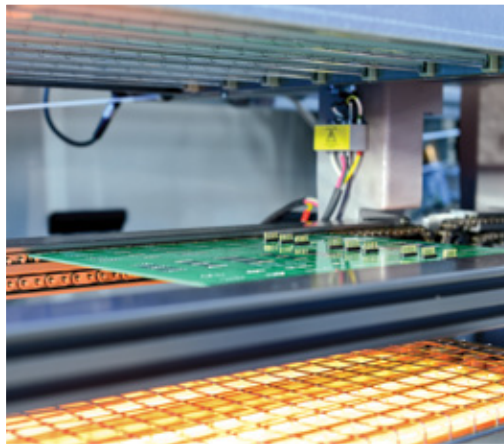
### Key standard features

- High frequency fluxing
- Inline preheating system
- SmartTeach programming
- Movable Electromagnetic solderpot
- Automatic waveheight and solderheight measurement
- Fiducial correction

### Key optional features

- Flux flow measurement
- Topside preheating (also during soldering)
- Closed loop preheating management
- Non-wettable or wettable nozzles
- Tilting for fine pitch soldering
- Bridge Prevention Technology (BPT)
- Process view camera
- Product warpage compensation

Specification	ZEVA M+
Max PCB or pallet size	510 x 510 mm (20 x 20 inch)
Max PCB weight	10 kg
Solder pot volume	8 kg
N2 consumption	20 L/min (25 L/min include SDC)
Maximum components height top side	120 mm (4.72 inch)
Power supply	3 x 400V 50/60 Hz
Machine size (L x W x H)	2370 x 1285 x 1220 mm (93.3 x 50.6 x 48 inch)



Bottom and optional top side quartz heaters



Rotatable non-wettable nozzles avoiding operator interference/ maintenance



Easily programmable allowing a fast process set up

ITW EAE is a division of Illinois Tool Works, Inc. It is a consolidation of all of its Electronic Assembly Equipment and Thermal Processing Technology. The group includes world-class products from MPM, Camalot, Electrovert (Speedline), Vitronics Soltec and Despatch.

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Soldering Solutions

